



TG-S606B

Thermal Compound

Version 1.280318



Thermal Compound

TG-S606B is a general purpose silicone based thermal grease which has a thermal conductivity of 1.8 W/mK, superior wetting characteristics, resulting in a very low thermal resistance and excellent long term reliability.

Features

- Good thermal conductivity
- Easy to assemble
- High stability
- Does not harden with time

Applications

Electronic components: IC, CPU, MOS
 LED, M/B, P/S, Heat Sink
 LCD, TV, Notebook PC, PC Telecom Device, Wireless Hub, etc.
 DDR II Module, DVD Applications, Hand-set applications, etc.

Properties

- ✓ REACH Compliant
- ✓ ROHS Compliant

Property	TG-S606B	Unit	Test Method
Colour	White	-	Visual
Thermal Conductivity	1.8	W/mK	ASTM D5470
Weight Loss	<0.5	%	ASTM E595
Density	2.3	g/cm ³	ASTM D792
Working Temperature	-40 to 180	°C	-
Volume Resistance	>10 ¹²	Ohm-cm	ASTM D257

Standard Packaging

Size	Packaging		Weight (gr)
	Pot		30g
	Pot		50g
	Pot		1 kg

Storage

TG-S606B has a self-life of eighteen (18) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened container at, or below 25°C.

T-Global Technology Limited
 1 & 2 Cosford Business Park, Central Park,
 Lutterworth, Leicestershire LE17 4QU U.K.

Tel: +44 (0)1455 553 510
 Email: sales@tglobaltechnology.com
 Web: www.tglobaltechnology.com
 Skype: tglobal.technology
 VAT #: GB 116 662 714

NOTICE: The information contained herein is to the best of our knowledge true and accurate. However, since the varied conditions of potential use are beyond our control, all recommendations or suggestions are presented without guarantee or responsibility on our part and users should make their own test to determine the suitability of our products in any specific situation. This product is sold without warranty either expressed or implied, of fitness for a particular purpose or otherwise, except that this product shall be of standard quality, and except to the extent otherwise stated in T-Global Technology Europe and North America's invoice, quotation, or order acknowledgment. We disclaim any and all liabilities incurred in connection with the use of information contained herein, or otherwise. All risks of such are assumed by the user. Furthermore, nothing contained herein shall be construed as a recommendation to use any process or to manufacture or to use any product in conflict with existing or future patents covering any product or material or its use.